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forming a bond between a second surface of said mounting surface and an interior surface of said first sidewall; and

snapping said image sensor substrate along a singulation street between said first sidewall of said first substrate and a second sidewall of a second substrate of said image sensor substrate.--

REMARKS

New Claims 26-30 have been added. Support for Claims 26-30 appears in the specification at least at page 2, line 9 to page 30, line 30 and in FIGS. 1-12B.

Claims 1-30 are pending in this application. If the Examiner has any questions relating to the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicants.

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Respectfully submitted,


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